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FAIRCHILD SEMICONDUCTOR®

December 2013

# IRL640A

## N-Channel Logic Level A-FET

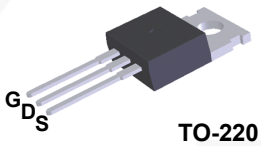
### 200 V, 18 A, 180 mΩ

## Description

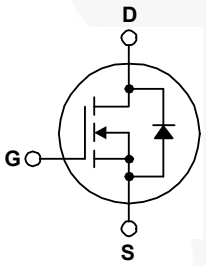
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

## Features

- 18 A, 200 V, $R_{DS(on)}$ = 180 mΩ @ $V_{GS}$ = 5 V
- Low Gate Charge (Typ. 40 nC)
- Low Crss (Typ. 95 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability
- Logic-Level Gate Drive




TO-220




## Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units |
|---|---|---|---|
| $V_{DSS}$ | Drain-to-Source Voltage | 200 | V |
| $I_D$ | Continuous Drain Current ($T_C$=25°C) | 18 | A |
| | Continuous Drain Current ($T_C$=100°C) | 11.4 | |
| $I_{DM}$ | Drain Current-Pulsed (1) | 63 | A |
| $V_{GS}$ | Gate-to-Source Voltage | ±20 | V |
| $E_{AS}$ | Single Pulsed Avalanche Energy (2) | 64 | mJ |
| $I_{AR}$ | Avalanche Current (1) | 18 | A |
| $E_{AR}$ | Repetitive Avalanche Energy (1) | 11 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (3) | 5 | V/ns |
| $P_D$ | Total Power Dissipation ($T_C$=25°C) | 110 | W |
| | Linear Derating Factor | 0.88 | W/°C |
| $T_J$ , $T_{STG}$ | Operating Junction and Storage Temperature Range | - 55 to +150 | °C |
| $T_L$ | Maximum Lead Temp. for Soldering Purposes, 1/8. from case for 5-seconds | 300 | |

## Thermal Resistance

| Symbol | Characteristic | Typ. | Max. | Units |
|---|---|---|---|---|
| $R_{\theta JC}$ | Junction-to-Case | -- | 1.14 | °C/W |
| $R_{\theta CS}$ | Case-to-Sink | 0.5 | -- | |
| $R_{\theta JA}$ | Junction-to-Ambient | -- | 62.5 | |

## Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|---|---|---|---|---|---|---|
| IRL640A | IRL640A | TO-220 | Tube | N/A | N/A | 50 units |

## Electrical Characteristics ($T_C$=25℃ unless otherwise specified)

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|---|---|---|---|---|---|---|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | 200 | -- | -- | V | $V_{GS}$=0V,$I_D$=250μA |
| $\Delta BV/\Delta T_J$ | Breakdown Voltage Temp. Coeff. | -- | 0.17 | -- | V/°C | $I_D$=250μA ***See Fig 7*** |
| $V_{GS(th)}$ | Gate Threshold Voltage | 1.0 | -- | 2.0 | V | $V_{DS}$=5V,$I_D$=250μA |
| $I_{GSS}$ | Gate-Source Leakage , Forward | -- | -- | 100 | nA | $V_{GS}$=20V |
| | Gate-Source Leakage , Reverse | -- | -- | -100 | | $V_{GS}$=-20V |
| $I_{DSS}$ | Drain-to-Source Leakage Current | -- | -- | 10 | μA | $V_{DS}$=200V |
| | | -- | -- | 100 | | $V_{DS}$=160V,$T_C$=125°C |
| $R_{DS(on)}$ | Static Drain-Source On-State Resistance | -- | -- | 0.18 | Ω | $V_{GS}$=5V,$I_D$=9A (4) |
| $g_{fs}$ | Forward Transconductance | -- | 13.3 | -- | ℧ | $V_{DS}$=40V,$I_D$=9A (4) |
| $C_{iss}$ | Input Capacitance | -- | 1310 | 1705 | pF | $V_{GS}$=0V,$V_{DS}$=25V,f =1MHz ***See Fig 5*** |
| $C_{oss}$ | Output Capacitance | -- | 200 | 250 | | |
| $C_{rss}$ | Reverse Transfer Capacitance | -- | 95 | 120 | | |
| $t_{d(on)}$ | Turn-On Delay Time | -- | 11 | 30 | ns | $V_{DD}$=100V,$I_D$=18A, $R_G$=4.6Ω ***See Fig 13*** (4) (5) |
| $t_r$ | Rise Time | -- | 8 | 25 | | |
| $t_{d(off)}$ | Turn-Off Delay Time | -- | 46 | 100 | | |
| $t_f$ | Fall Time | -- | 15 | 40 | | |
| $Q_g$ | Total Gate Charge | -- | 40 | 56 | nC | $V_{DS}$=160V,$V_{GS}$=5V, $I_D$=18A ***See Fig 6 & Fig 12*** (4) (5) |
| $Q_{gs}$ | Gate-Source Charge | -- | 6.8 | -- | | |
| $Q_{gd}$ | Gate-Drain (. Miller. ) Charge | -- | 18.6 | -- | | |

## Source-Drain Diode Ratings and Characteristics

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|---|---|---|---|---|---|---|
| $I_S$ | Continuous Source Current | -- | -- | 18 | A | Integral reverse pn-diode in the MOSFET |
| $I_{SM}$ | Pulsed-Source Current (1) | -- | -- | 63 | | |
| $V_{SD}$ | Diode Forward Voltage (4) | -- | -- | 1.5 | V | $T_J$=25°C,$I_S$=18A,$V_{GS}$=0V |
| $t_{rr}$ | Reverse Recovery Time | -- | 224 | -- | ns | $T_J$=25°C,$I_F$=18A |
| $Q_{rr}$ | Reverse Recovery Charge | -- | 1.55 | -- | μC | $di_F/dt$=100A/μs (4) |

**Notes;**

(1) Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

(2) L=0.3mH, $I_{AS}$=18A, $V_{DD}$=50V, $R_G$=27Ω, Starting $T_J$=25°C

(3) $I_{SD}$ ≤ 18A, di/dt ≤ 260A/μs, $V_{DD}$ ≤ $BV_{DSS}$ , Starting $T_J$=25°C

(4) Pulse Test: Pulse Width = 250μs, Duty Cycle ≤ 2%

(5) Essentially Independent of Operating Temperature

## Typical Characteristics

Fig 1. Output Characteristics

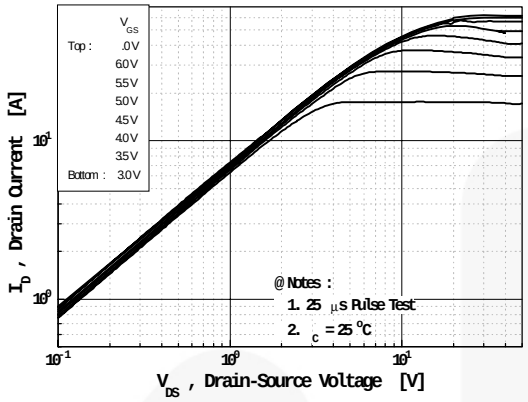



Fig 2. Transfer Characteristics

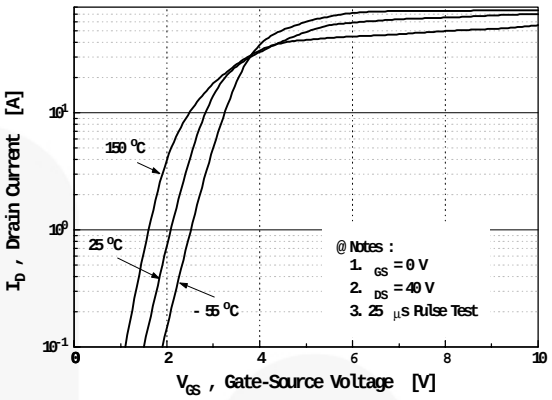



Fig 3. On-Resistance vs. Drain Current

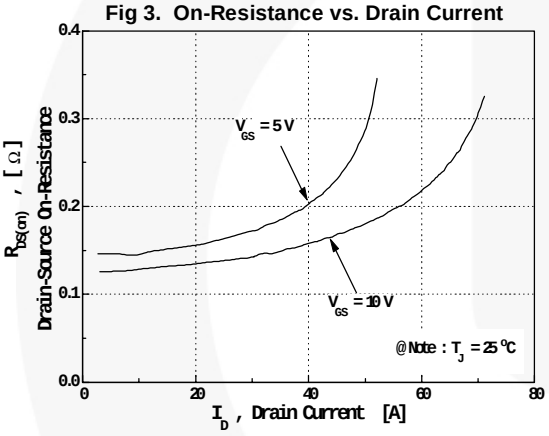



Fig 4. Source-Drain Diode Forward Voltage

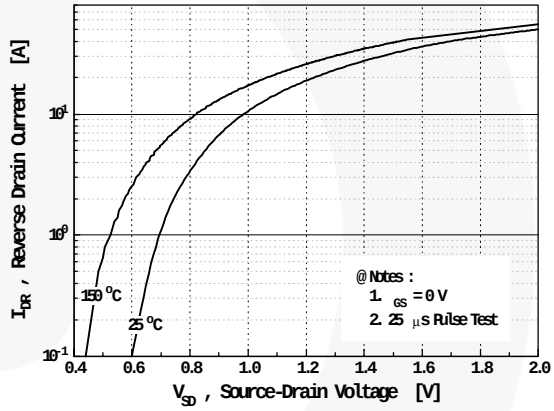



Fig 5. Capacitance vs. Drain-Source Voltage

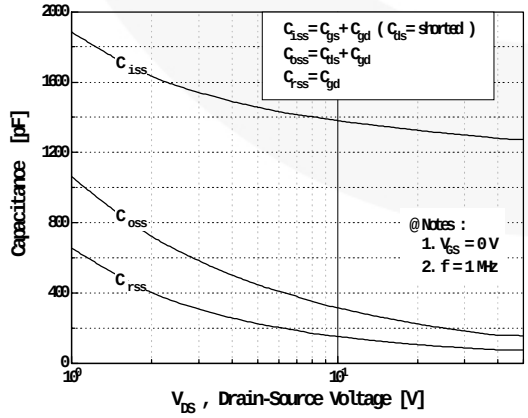
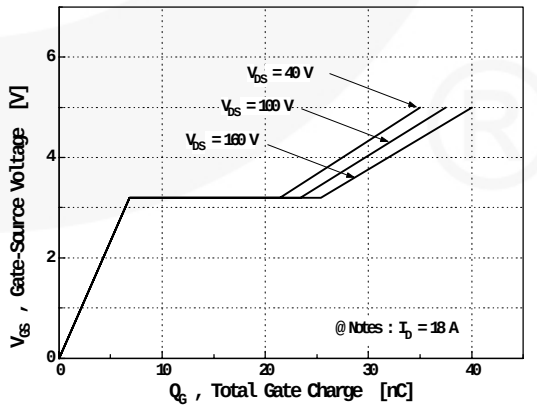



Fig 6. Gate Charge vs. Gate-Source Voltage



## Typical Characteristics (continued)

Fig 7. Breakdown Voltage vs. Temperature

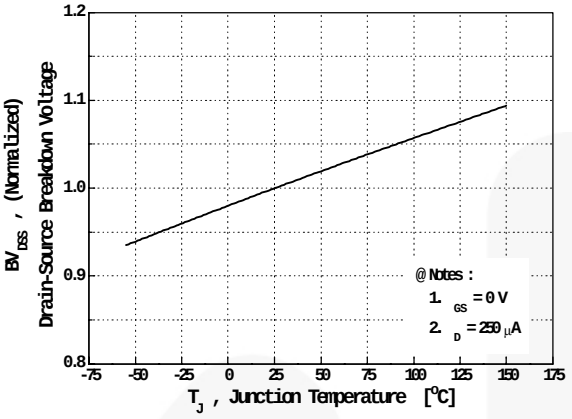



Fig 8. On-Resistance vs. Temperature

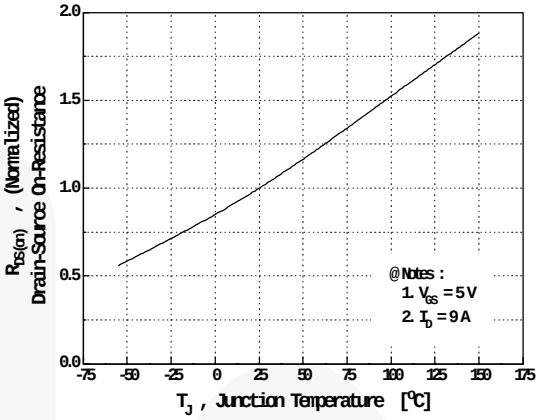



Fig 9. Max. Safe Operating Area

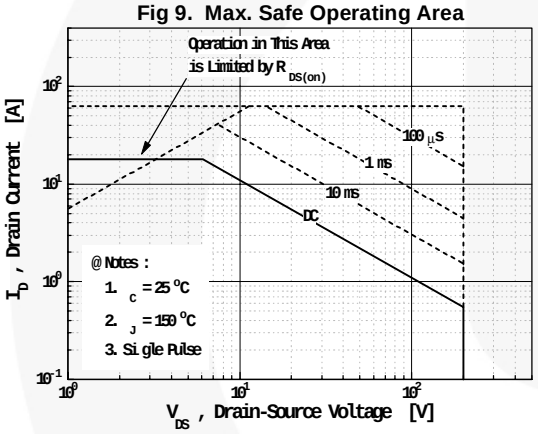



Fig 10. Max. Drain Current vs. Case Temperature

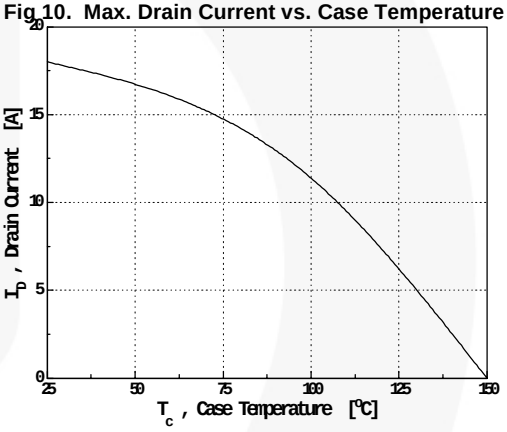
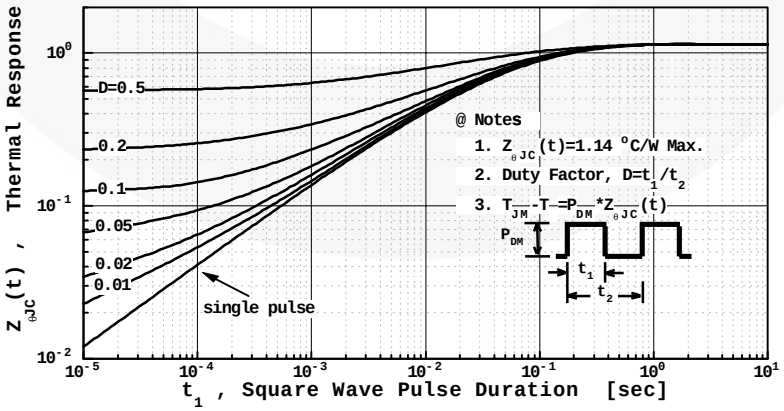



Fig 11. Thermal Response



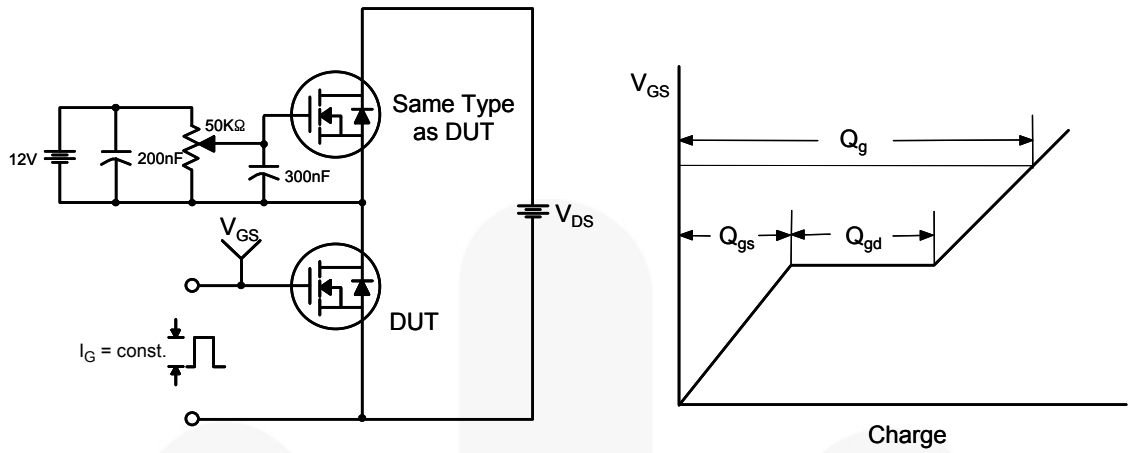



**Figure 12. Gate Charge Test Circuit & Waveform**

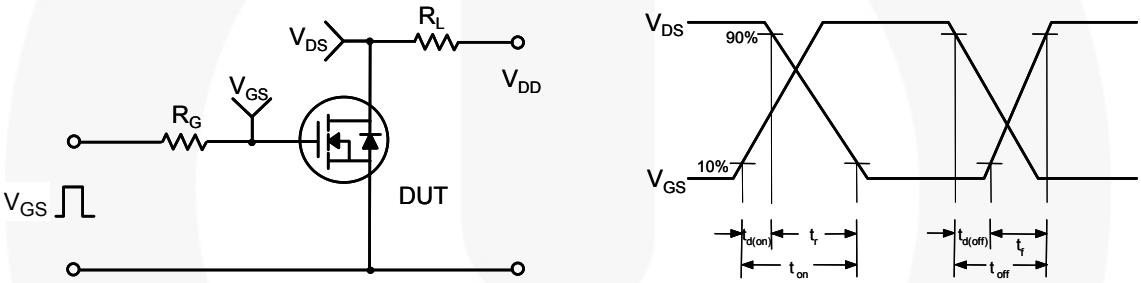



**Figure 13. Resistive Switching Test Circuit & Waveforms**

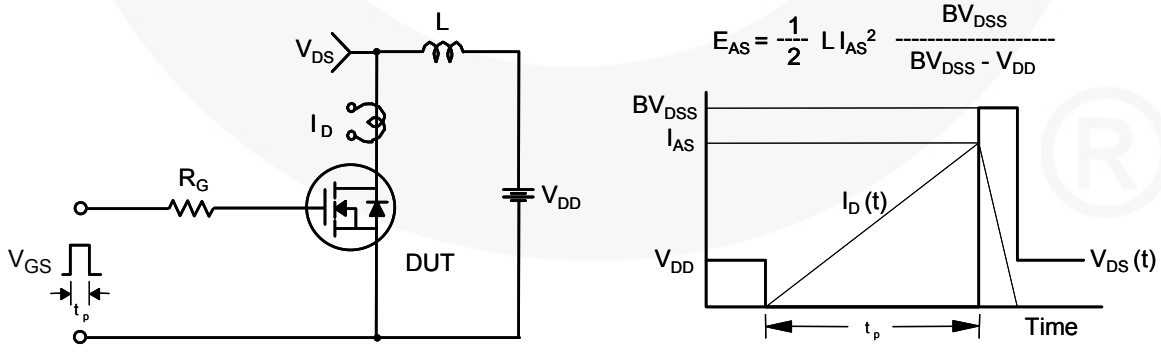



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

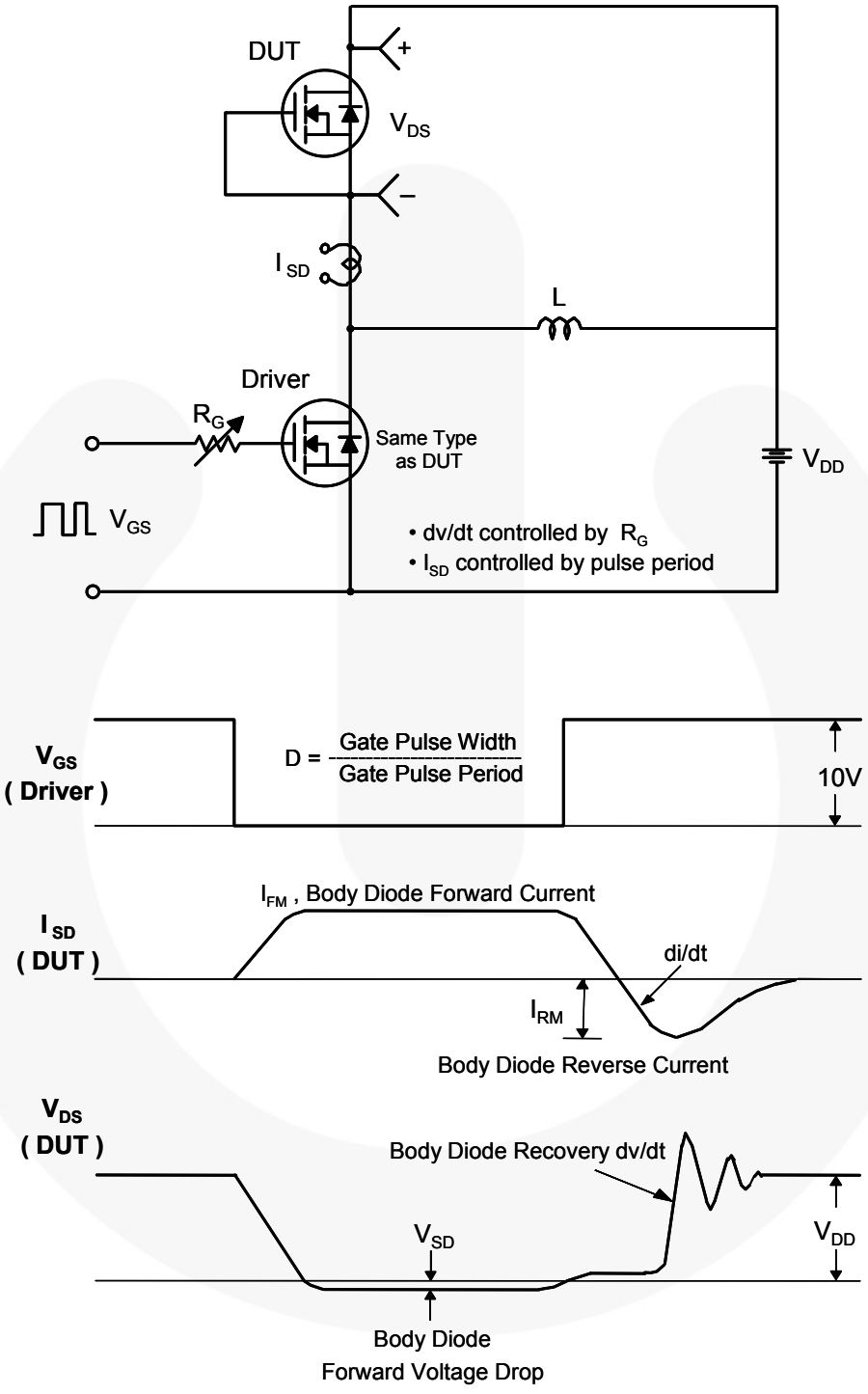



**Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms**

## Mechanical Dimensions

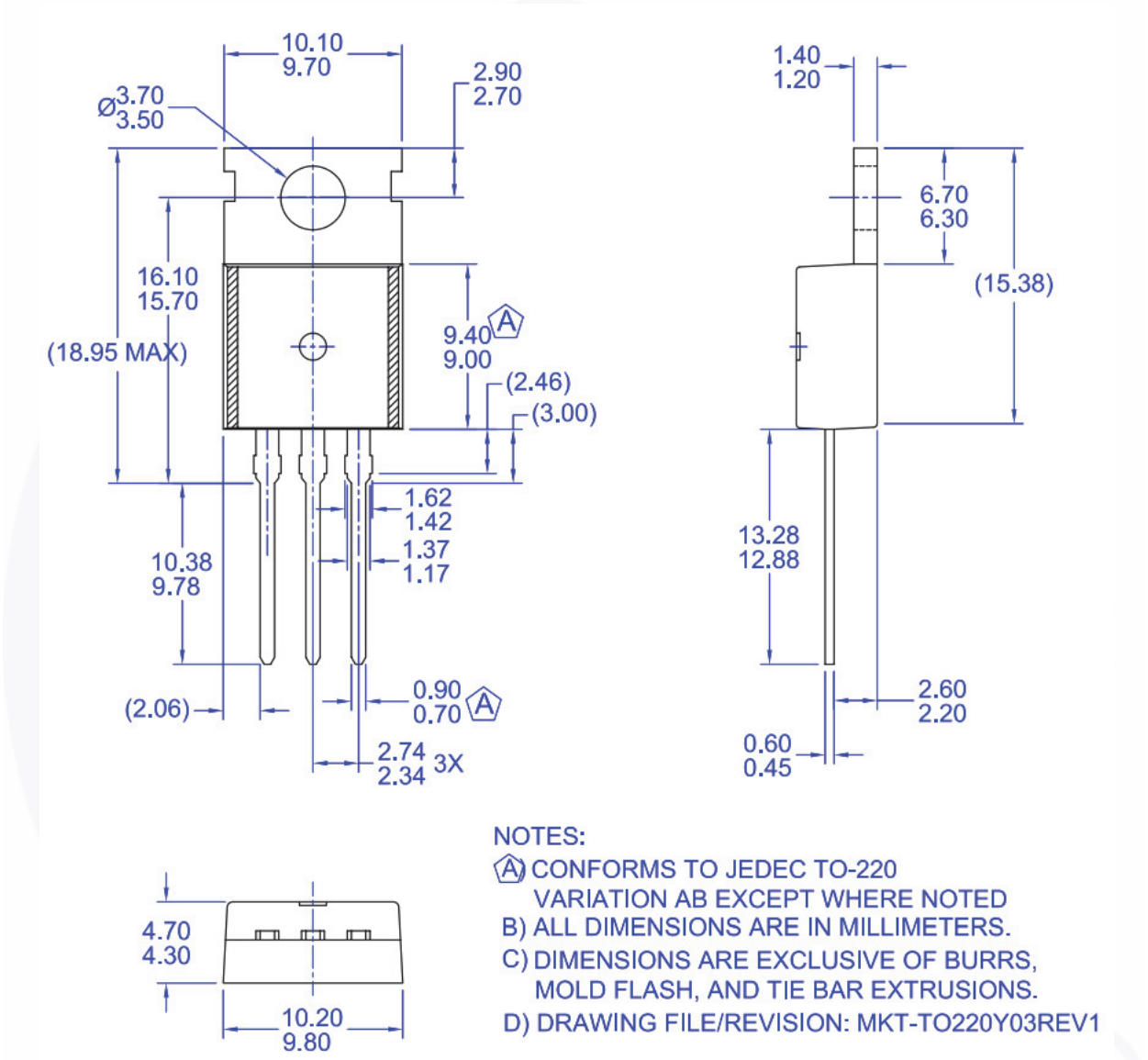



**Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB**

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